

CLAIMS

1. A curable organopolysiloxane composition comprising:

(A) a straight-chain organopolysiloxane having per molecule at least two silicon-bonded alkenyl groups and at least one silicon-bonded aryl group;

5 (B) a branched-chain organopolysiloxane with siloxane units represented by the general formula:



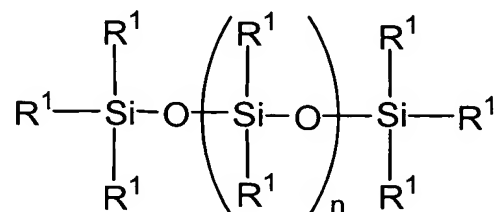
where R is a substituted or unsubstituted monovalent hydrocarbon group, and where component (B) has per molecule, at least one silicon-bonded alkenyl group and at least one  
10 silicon-bonded aryl group, and where component (B) is used in a weight ratio of 1/99 to 99/1 based on the weight of component (A);

(C) an organopolysiloxane having per molecule at least two silicon-bonded hydrogen atoms, where component (C) is used in an amount of 1 to 200 parts by weight for each 100 parts by weight of the total weight of parts (A) and (B); and

15 (D) a hydrosilylation catalyst in an amount sufficient to promote curing of the composition.

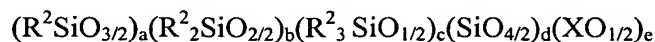
2. The curable organopolysiloxane composition of claim 1, where component (A) has a content of silicon-bonded aryl groups not less than 40 mole % of all silicon-bonded organic groups in component (A).

20 3. The curable organopolysiloxane composition of claim 1, where component (A) is an organopolysiloxane represented by the general formula:



where each R<sup>1</sup> comprises the same or different substituted or unsubstituted monovalent hydrocarbon groups, at least two R<sup>1</sup>'s comprise alkenyl groups, at least one R<sup>1</sup> comprises  
25 an aryl group, and n is an integer from 5 to 1000.

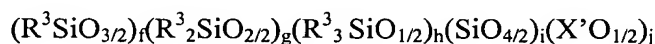
4. The curable organopolysiloxane composition of claim 1, where component (B) has average unit formula:



where each  $R^2$  is the same or different substituted or unsubstituted monovalent

5 hydrocarbon group, 0.1 to 40 mole % of all  $R^2$ 's are alkenyl groups, more than 10 mole % of all  $R^2$ 's are aryl groups, X is a hydrogen atom or an alkyl group, a is a positive number, b is 0 or a positive number, c is 0 or a positive number, d is 0 or a positive number, e is 0 or a positive number, b/a is 0 to 10, c/a is 0 to 0.5, d/(a + b + c + d) is 0 to 0.3, and e/(a + b + c + d) is 0 to 0.4.

10 5. The curable organopolysiloxane composition of claim 1, where all or a portion of component (C) has average unit formula:



where each  $R^3$  is the same or different alkenyl groups, substituted or unsubstituted

monovalent hydrocarbon groups, or hydrogen atoms; 0.1 to 40 mole % of all  $R^3$ 's are

15 hydrogen atoms; more than 10 mole % of all  $R^3$ 's are aryl groups; X' is a hydrogen atom or an alkyl group, f is a positive number, g is 0 or a positive number, h is 0 or a positive number, i is 0 or a positive number, j is 0 or a positive number, g/f is 0 to 10, h/f is 0 to 0.5, i/(f + g + h + i) is 0 to 0.3, and j/(f + g + h + i) is 0 to 0.4.

6. The curable organopolysiloxane composition of claim 1, where index of refraction at  
20 25°C in visible light having a wavelength of 589 nm passing through an object obtained by curing the curable organopolysiloxane composition of any of claims 1 to 5 is equal to or exceeds 1.5.

7. The curable organopolysiloxane composition of claim 1, where coefficient of light  
25 permeation at 25°C through an object obtained by curing the curable organopolysiloxane composition of any of claims 1 to 5 is equal to or exceeds 80%.

8. A semiconductor device coated with a cured coating made from the curable organopolysiloxane according to any of claims 1 to 5.

9. The semiconductor device of claim 8, where said semiconductor device comprises a light-emitting element.